AgPd Termination Conductive Glue Mounting Chip Multilayer Ceramic Capacitors for Automotive

GCG1887U2A152JA01_ (0603, U2J:EIA, 1500pF, DC100V)

_: packaging code

Reference Sheet

1.Scope

This product specification is applied to Chip Multilayer Ceramic Capacitors limited to Conductive Glue Mounting used for Automotive Electronic equipment.

2.MURATA Part NO. System



3. Type & Dimensions



(Unit:mr							
(1)-1 L	(1)-2 W	(2) T	e	g			
1.6±0.2	0.8±0.1	0.8±0.1	0.2 to 0.5	0.5 min.			

4.Rated value

(3) Temperature Characteristics (Public STD Code):U2J(EIA)		(4) Rated	(5) Nominal	(6) Capacitance	Specifications and Test Methods
Temp. coeff or Cap. Change	Temp. Range (Ref.Temp.)	Range Voltage		Tolerance	(Operating Temp. Range)
-750±120 ppm/°C	25 to 85 °C (25 °C)	DC 100 V	1500 pF	±5 %	-55 to 125 °C

5.Package

mark	(8) Packaging	Packaging Unit
D	∳180mm Reel PAPER W8P4	4000 pcs./Reel
J	∮330mm Reel PAPER W8P4	10000 pcs./Reel

Product specifications in this catalog are as of Oct.17,2017,and are subject to change or obsolescence without notice. Please consult the approval sheet before ordering. Please read rating and !Cautions first.

■AEC-Q200 Murata Standard Specification and Test Methods

			Specifi	ication.						
١o) Test Item	Temperature Compensating Type	High Dielectric Type			AE	C-Q200	Test Method	
1	Pre-and Post- Electrical Test				-					
2	High Tempera	ture	The measured and observed charact	eristics should satisfy the	Fix the capacitor to the test substrate in the same manner and					
	Exposure (Sto		specifications in the following table.		under the same conditions as No.16.					
		Appearance	No marking defects			Set the capacitor for 1000+/-12hours at 150+/-3°C. Set for 24+/-2hours at room temperature, then measure.				
		Capacitance	Within +/-2.5% or +/-0.25pF	Within +/-12.5%		. 2417	2110010 011001111	ompora		0.
		Change	(Whichever is larger)		• Ini	ial me	asurement for hic	h dielec	tric constant type	
		Q or D.F.	30pF min. : Q≧1000	R7/L8 : 0.05 max.	_		-		0 °C for 1hour an	d then sit
		Q 01 D.1 .	30pF max.: Q ≧400+20C	R9 : 0.075 max.					Perform the initia	
				K9 . 0.075 max.		., 2.10		orataro.		. modouromon
		I.R.	C: Nominal Capacitance(pF)	hishover is smaller)	4					
		25°C	More than 10000M Ω or 500 Ω · F (Whichever is smaller) R9 : More than 3000M Ω or 150 Ω · F (Whichever is smaller)							
3	Temperature C	Cycling	The measured and observed charact	eristics should satisfy the	Fix th	e capa	citor to the test s	ubstrate	in the same man	ner and
			specifications in the following table.		under	the sa	ame conditions as	8 No.16.	Perform the 1000) cycles
		Appearance	No marking defects						listed in the follov ture, then measure	•
		Capacitance	Within +/-2.5% or +/-0.25pF	Within +/-10.0%	1					
		Change	(Whichever is larger)			Step	1	2	3	4
			,			Temp.	Min. Operating	Room	Max. Operating	Room
		Q or D.F.	30pF min. : Q≧1000	R7/L8 W.V.: 25Vmin.: 0.03 max.	+	(°C)	Temp. +0/-3	Temp.	Temp. +3/-0	Temp.
			30pF max.: Q ≧400+20C	W.V.: 16V : 0.05 max		Time				
			C: Nominal Capacitance (pF)	R9 : 0.075 max.		Time (min)	15+/-3	1	15+/-3	1
		1.0			• Ini	ial mo	asurament for his	h dioloc	tric constant type	
		I.R.	More than $10000M\Omega$ or $500\Omega \cdot F$			-			م مام م	
	25°C		(Whichever is smaller)						0 °C for 1hour an Perform the initia	
	Destructive									
4					Dor E	14-460)			
4		roio.	No defects or abnormalities		Per E	IA-469).			
	Physical Analy			aviation about action the						
			The measured and observed charact	eristics should satisfy the	Fix th	e capa	citor to the test s		in the same man	ner and
	Physical Analy			eristics should satisfy the	Fix th under	e capa the sa	icitor to the test s ame conditions as	s No.16.		
	Physical Analy		The measured and observed charact	eristics should satisfy the	Fix th under Apply	e capa the sa the 24	icitor to the test s ame conditions as I-hour heat (25°C	s No.16. to 65°C)) and humidity (80	
	Physical Analy	stance	The measured and observed charact specifications in the following table.	eristics should satisfy the	Fix th under Apply treatn	e capa the sa the 24 nent sh	acitor to the test s ame conditions as I-hour heat (25°C nown below, 10 c	No.16. to 65°C) onsecuti) and humidity (80 ve times.	1%RH to 98%R
4	Physical Analy		The measured and observed charact	teristics should satisfy the	Fix th under Apply treatn Set fo Tempe	e capa the sa the 24 nent sh or 24+/	citor to the test s ame conditions as I-hour heat (25°C nown below, 10 c -2hours at room t	No.16. to 65°C) onsecuti) and humidity (80 ve times. ture, then measure _{Humidit}	9%RH to 98%R e.
	Physical Analy	Appearance	The measured and observed charact specifications in the following table. No marking defects	-	Fix th under Apply treatn Set fo	e capa the sa the 24 nent sh or 24+/	icitor to the test s ame conditions as I-hour heat (25°C nown below, 10 cr -2hours at room t	No.16. to 65°C) onsecuti emperat) and humidity (80 ve times. ture, then measure _{Humidit}	9%RH to 98%R e.
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5	Physical Analy Moisture Resis	Appearance Capacitance Change Q or D.F. I.R. 25°C	The measured and observed charact specifications in the following table. No marking defects Within +/-3.0% or +/-0.30pF (Whichever is larger) $30pF min. : Q \ge 350$ $10pF and over, 30pF and below:Q \ge 275+5C/210pF max.: Q \ge 200+10CC: Nominal Capacitance(pF)More than 10000MΩ or 500Ω+ F (WR9 : More than 3000MΩ or 150 Ω+ F$	Within +/-12.5% R7/L8 : 0.05 max. R9 : 0.075 max. hichever is smaller)	Fix th under Apply treatm Set fc C C C C C C C C C C C C C C C C C C C	e capa the sa the 24-/ rature the rational shores of the sa the rational shores of the sale	citor to the test s ame conditions as I-hour heat (25°C hown below, 10 cr -2hours at room t Humidity 90~98% Hu	No.16. to 65°C) ponsecuti emperat Humi di ty 80~98% ************************************) and humidity (80 ve times. ture, then measure Humidity 80~98) 90~98% 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	%RH to 98%R e.
5	Physical Analy Moisture Resis	Appearance Capacitance Change Q or D.F. I.R. 25°C	The measured and observed charact specifications in the following table. No marking defects Within +/-3.0% or +/-0.30pF (Whichever is larger) $30pF$ min. : Q \geq 350 10pF and over, 30pF and below: Q \geq 275+5C/2 $10pF$ max.: Q \geq 200+10C C: Nominal Capacitance(pF) More than 10000MΩ or 500Ω+ F (W R9 : More than 3000MΩ or 150 Ω+ F The measured and observed charact specifications in the following table. No marking defects	Within +/-12.5% R7/L8 : 0.05 max. R9 : 0.075 max. hichever is smaller)	Fix th under Apply treatm Set fc Tempe (°C) Tempe (°C) Te	e capa the sa the 24+/ rature the rational shore and the sa the sa the rational shore and the sa the s	citor to the test s ame conditions as I-hour heat (25°C hown below, 10 cr -2hours at room t Humidity 90~98% Hu	No.16. to 65°C) onsecuti emperat Humi di ty 80~98% c 0ne cy % c 0ne cy 9 10 11 c to delec 150+0/-1 berature. ubstrate \$ No.16. .3+0.2/- 5% RH h) and humidity (80 ve times. ture, then measure Humidity 80~98 90~98 90~98 10 10 10 10 10 100+ to be a second to be a second to be a second to be a second to be a second to be a second to be a second	%RH to 98%R e. y i Humidity 90~98% i Humidity 1 1 1 1 1 2 2 21 22 23 24 d then sit I measuremen ner and resister) /-12hours.
ō	Physical Analy Moisture Resis	Appearance Capacitance Change Q or D.F. I.R. 25°C	The measured and observed charact specifications in the following table. No marking defects Within +/-3.0% or +/-0.30pF (Whichever is larger) $30pF$ min. : Q \geq 350 10pF and over, 30pF and below: Q \geq 275+5C/2 $10pF$ max.: Q \geq 200+10C C: Nominal Capacitance(pF) More than 10000MΩ or 500Ω+ F (W R9 : More than 3000MΩ or 150 Ω+ F	Within +/-12.5% R7/L8 : 0.05 max. R9 : 0.075 max. hichever is smaller)	Fix th under Apply treatm Set fc Tempe (°C) Tempe (°C) Te	e capa the sa the 24+/ rature the rational shore and the sa the sa the rational shore and the sa the s	citor to the test s ame conditions as I-hour heat (25°C hown below, 10 cr -2hours at room t Humidity 90~98% Hu	No.16. to 65°C) onsecuti emperat Humi di ty 80~98% c 0ne cy % c 0ne cy 9 10 11 c to delec 150+0/-1 berature. ubstrate \$ No.16. .3+0.2/- 5% RH h) and humidity (80 ve times. ture, then measure Humidity 80~98) 90~98% 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	%RH to 98%R e. y i Humidity 90~98% i Humidity 1 1 1 1 1 2 2 21 22 23 24 d then sit I measuremen ner and resister) /-12hours.
ō	Physical Analy Moisture Resis	Appearance Capacitance Change Q or D.F. I.R. 25°C ty Appearance	The measured and observed charact specifications in the following table. No marking defects Within +/-3.0% or +/-0.30pF (Whichever is larger) $30pF$ min. : Q \geq 350 10pF and over, 30pF and below: Q \geq 275+5C/2 $10pF$ max.: Q \geq 200+10C C: Nominal Capacitance(pF) More than 10000MΩ or 500Ω+ F (W R9 : More than 3000MΩ or 150 Ω+ F The measured and observed charact specifications in the following table. No marking defects	Within +/-12.5% R7/L8 : 0.05 max. R9 : 0.075 max. hichever is smaller) • (Whichever is smaller) • (Whichever is smaller)	Fix th under Apply treatm Set fc Tempe (°C) Tempe (°C)	e capa the sa the 24+/ rature the rational shore the sa the rational shore the sa the rational shore the sa the	citor to the test s ame conditions as I-hour heat (25°C hown below, 10 cr -2hours at room t Humidity 90~98% Hu	No.16. to 65°C) prosecuti emperat Humi di ty 80~98% C C One cy % C One cy % C One cy % C One cy % C One cy % C One cy % C One cy % C One cy % C One cy % C One cy % C C C C C C C C C C C C C C C C C C) and humidity (80 ve times. ture, then measure Humidity 80~98 90~98 90~98 10 10 10 10 10 10 12 13 14 15 16 17 18 The Hours tric constant type 0 °C for 1 hour an Perform the initia in the same mania 0Vdc (add 6.8kΩ umidity for 1000+ com temperature,	%RH to 98%R e. y i Humidity 90~98% i Humidity 1 1 1 1 1 2 2 21 22 23 24 d then sit I measuremen ner and resister) /-12hours.
5	Physical Analy Moisture Resis	Appearance Capacitance Change Q or D.F. I.R. 25°C ty Appearance Capacitance Capacitance	The measured and observed charact specifications in the following table. No marking defects Within +/-3.0% or +/-0.30pF (Whichever is larger) $30pF$ min. : Q \geq 350 10pF and over, 30pF and below: Q \geq 275+5C/2 $10pF$ max.: Q \geq 200+10C C: Nominal Capacitance(pF) More than 10000MΩ or 500Ω · F (W R9 : More than 3000MΩ or 150 Ω · F The measured and observed charact specifications in the following table. No marking defects Within +/-3.0% or +/-0.30pF	Within +/-12.5% R7/L8 : 0.05 max. R9 : 0.075 max. hichever is smaller) • (Whichever is smaller) • (Whichever is smaller)	Fix th under Apply treatm Set fc Tempe (°C) Tempe (°C)	e capa the sa the 24+/ rature the rational shore the sa the rational shore the sa the rational shore the sa the	citor to the test s ame conditions as I-hour heat (25°C hown below, 10 cr -2hours at room t Humidity 90~99% Humidity Public Humidity 90~99% Humidity Humidity 90~99% Humidity Humidity 90~99% Humidity Humidity Humidity 90~99% Humidity Humidity Humidity 90~99% Humidity Hu	No.16. to 65°C) prosecuti emperat Humi di ty 80~98% C C One cy % C One cy % C One cy % C One cy % C One cy % C One cy % C One cy % C One cy % C One cy % C One cy % C C C C C C C C C C C C C C C C C C) and humidity (80 ve times. ture, then measure Humidity 80~98 90~98 90~98 10 10 10 10 10 10 12 13 14 15 16 17 18 The Hours tric constant type 0 °C for 1 hour an Perform the initia in the same mania 0Vdc (add 6.8kΩ umidity for 1000+ com temperature,	%RH to 98%R e. y i Humidity 90~98% i Humidity 1 1 1 1 1 2 2 21 22 23 24 d then sit I measuremen ner and resister) /-12hours.
ō	Physical Analy Moisture Resis	Appearance Capacitance Change Q or D.F. I.R. 25°C ty Appearance Capacitance Change	The measured and observed charact specifications in the following table. No marking defects Within +/-3.0% or +/-0.30pF (Whichever is larger) $30pF$ min. : Q \geq 350 10pF and over, 30pF and below: Q \geq 275+5C/2 $10pF$ max.: Q \geq 200+10C C: Nominal Capacitance(pF) More than 10000MΩ or 500Ω · F (W R9 : More than 3000MΩ or 150 Ω · F The measured and observed charact specifications in the following table. No marking defects Within +/-3.0% or +/-0.30pF (Whichever is larger)	Within +/-12.5% R7/L8 : 0.05 max. R9 : 0.075 max. hichever is smaller) (Whichever is smaller) (Whichever is smaller) Within +/-12.5%	Fix th under Apply treatm Set fc C Set fc C C C C C C C C C C C C C C C C C C C	e capa the sat the 24-/ rature the rational saturation the saturation of the saturation the sat the sat th	citor to the test s ame conditions as I-hour heat (25°C hown below, 10 cr -2hours at room t Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 12 a 4 5 6 7 Humidity asurement for hig eat treatment at fours as ted voltage and 1 and 80%RH to 88 d set for 24+/-2ho discharge current	No.16. to 65°C) prosecuti emperat Humi di ty 80~98% C C One cy % C One cy % C One cy % C One cy % C One cy % C One cy % C One cy % C One cy % C One cy % C One cy % C C C C C C C C C C C C C C C C C C) and humidity (80 ve times. ture, then measure Humidity 80~98 90~98 90~98 10 10 10 10 10 10 12 13 14 15 16 17 18 The Hours tric constant type 0 °C for 1 hour an Perform the initia in the same mania 0Vdc (add 6.8kΩ umidity for 1000+ com temperature,	%RH to 98%R e. y i Humidity 90~98% i Humidity 1 1 1 1 1 2 2 21 22 23 24 d then sit I measuremen ner and resister) /-12hours.
5	Physical Analy Moisture Resis	Appearance Capacitance Change Q or D.F. I.R. 25°C ty Appearance Capacitance Change	The measured and observed charact specifications in the following table. No marking defects Within +/-3.0% or +/-0.30pF (Whichever is larger) $30pF$ min. : Q \geq 350 10pF and over, 30pF and below: Q \geq 275+5C/2 $10pF$ max.: Q \geq 200+10C C: Nominal Capacitance(pF) More than 10000MΩ or 500Ω · F (W R9 : More than 3000MΩ or 150 Ω · F The measured and observed charact specifications in the following table. No marking defects Within +/-3.0% or +/-0.30pF (Whichever is larger) $30pF$ and over: Q \geq 200	Within +/-12.5% R7/L8 : 0.05 max. R9 : 0.075 max. hichever is smaller) f (Whichever is smaller) teristics should satisfy the Within +/-12.5% R7/L8 : 0.05 max.	Fix th under Apply treatm Set fc Tempe (°C Te	e capa the sa the 24+/ rature the rational shore and the sa the rational shore and the sa the sa the rational shore and the sa the sa t	citor to the test s ame conditions as I-hour heat (25°C nown below, 10 cr -2hours at room t Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 90~98% Humidity 12 3 4 5 6 7 1 asurement for hig eat treatment at fours as ted voltage and 1 and 80% RH to 88 d set for 24+/-2ho discharge current	No.16. to 65°C) prosecuti emperat Humi di ty 80~98% ************************************) and humidity (80 ve times. ture, then measure Humidity 80~98 90~98 90~98 10 10 10 100 12 13 14 15 16 17 18 The Hours tric constant type 0 °C for 1 hour an Perform the initia in the same manu 0Vdc (add 6.8kΩ umidity for 1000+ com temperature, than 50mA.	%RH to 98%R e. y humidity 90~98% 10~98%10~98% 10~98% 10~98% 10~98% 10~98%10~98% 10~98% 10~98%10~98% 10~98% 10~98%10~98% 10~98% 10~98%10~98% 10~98%10~98% 10~98%10~98% 10~98%10~98% 10~98%10~98% 10~98%10~98% 10~98%10~98% 10~98%10~98%10~98% 10~98%10~98%10~98% 10~98%10~98%10~98%10~98% 10~98%10~98%10~98%10~98%10~98% 10~98%10~98%10~98%10~98% 10~98%10~98%10~98%10~98%10~98%10~98%10~98%10~98%10~98%10~98%10~98%10~98%10~98% 10~98%10~98%10~98%10~98%10~98%10~98%10~98%10~98%10~98%10~98%10~98%10~98%10~98%10~9
5	Physical Analy Moisture Resis	Appearance Capacitance Change Q or D.F. I.R. 25°C ty Appearance Capacitance Change	The measured and observed charact specifications in the following table. No marking defects Within +/-3.0% or +/-0.30pF (Whichever is larger) $30pF$ min. : Q \geq 350 10pF and over, 30pF and below: Q \geq 275+5C/2 $10pF$ max.: Q \geq 200+10C C: Nominal Capacitance(pF) More than 10000MΩ or 500Ω · F (W R9 : More than 3000MΩ or 150 Ω · F Specifications in the following table. No marking defects Within +/-3.0% or +/-0.30pF (Whichever is larger) $30pF$ and over: Q \geq 200 $30pF$ and over: Q \geq 100+10C/3	Within +/-12.5% R7/L8 : 0.05 max. R9 : 0.075 max. hichever is smaller) f (Whichever is smaller) teristics should satisfy the Within +/-12.5% R7/L8 : 0.05 max.	Fix th under Apply treatm Set fc Tempe (°C Te	e capa the sat the 24-/ rature the rational saturation the rational saturation the rational saturation the sat the sat t	citor to the test s ame conditions as I-hour heat (25°C nown below, 10 cr -2hours at room t Humi di ty 90~98% Humi di ty	No.16. to 65°C) prosecuti emperat Humi di ty 80~98% C C C C C C C C C C C C C C C C C C C) and humidity (80 ve times. ture, then measure Humidity 80~98 90~98 90~98 10 - 10 - 10 12 13 14 15 16 17 18 - Hours tric constant type 0 °C for 1 hour an Perform the initia in the same manifold 0 °C (add 6.8kΩ umidity for 1000+ com temperature, than 50mA.	%RH to 98%R e. Humi di ty 90~98% 10



AEC-Q200 Murata Standard Specification and Test Methods

			Spec	ification.	1				
١o	AEC-Q20	0 Test Item	Temperature		-		AEC-Q200 T	est Method	
	-		Compensating Type	High Dielectric Type					
7	Operational Lif	e	The measured and observed characteristics should satisfy the specifications in the following table.			Fix the capacitor to the test substrate in the same manner and under the same conditions as No.16.			
		Appearance	No marking defects					00+/-12 hours at max operating	
		, ppcaranoc				Apply 150% of the rated voltage for 1000+/-12 hours at max. operating temp.+/-3°C.			
		Capacitance	Within +/-3.0% or +/-0.30pF	Within +/-12.5%			nours at room temperatur	e, then measure.	
		Change	(Whichever is larger)		The	charge/dis	charge current is less that	an 50mA.	
		Q or D.F.	30pF min. : Q≧350	R7/L8 : 0.05 max.					
			10pF and over, 30pF and below:	R9 : 0.075 max.			rement for high dielectric		
			Q≧275+5C/2 10pF max.: Q ≧200+10C			•	•	ating temp. +/-3°C for 1hour temperature, then measure.	
			C: Nominal Capacitance(pF)		anu	then let sit	101 24+/-2110013 at 100111	temperature, men measure.	
		I.R.	More than 1,000M Ω or 50 $\Omega \cdot F$						
		25°C	(Whichever is smaller)						
3	External Visua	nal Visual No defects or abnormalities		Visu	al inspecti	on			
9	Physical Dimer	nsion	Within the specified dimensions		Usir	ng Measuri	ng instrument of dimension	on.	
0	Resistance to	Appearance	No marking defects		Per	MIL-STD-2	202 Method 215		
	Solvents						part (by volume) of isopro	pyl alcohol	
		Capacitance	Within the specified initial value.		1		parts (by volume) of mine		
							rpene defluxer	1	
		Q or D.F.	Within the specified initial value.		-		parts (by volume) of wat	er	
							, ,		
		I.R.	More than 10000MΩ or 500Ω ·F	1part (by volume) of propylene glycol monomethyl ether 1 part (by volume) of monoethanolamine					
		25°C	(Whichever is smaller)						
1	Mechanical	Appearance	No marking defects			the canacit	or to the test substrate in	the same manner and	
	Shock	Арреаганее				•	ns as No.16.		
		Capacitance	Within the specified initial value.		-			be applied along 3 mutually	
							axes of the test specimer		
		Q or D.F.	Within the specified initial value.				est pulse should be Half-		
						ation :0.5m	s, peak value:1500g and	velocity change: 4.7m/s.	
		I.R.	More than 10000MΩ or 500Ω ·F						
		25°C	(Whichever is smaller)						
12	Vibration	Appearance	No marking defects				or to the test substrate in	the same manner and	
		Canaaitanaa	Within the energified initial value		-		ns as No.16.	aimple harmonia motion having	
		Capacitance	Within the specified initial value.					simple harmonic motion having cy being varied uniformly	
		Q or D.F.	Within the specified initial value.		-				
					between the approximate limits of 10Hz and 2000Hz. The frequency range, from 10Hz to 2000Hz and return to 10Hz,				
		I.R.	More than $10000M\Omega$ or $500\Omega \cdot F$		-		ersed in approximately 20		
		25°C	(Whichever is smaller)		This motion should be applied for 12 cycles in each 3 mutually				
			(directions (total of 36 time		
13	Thermal Shock		The measured and observed char	acteristics should eatisfy the	Fiv	the canacit	or to the test substrate in	the same manner and	
. 0		x .	specifications in the following table				e conditions as No.16.	and same manner dilu	
		Appearance	No marking defects		-			e two heat treatments listed	
				1	in th	e following	table(Maximum transfer	time is 20seconds).	
		Capacitance	Within +/-2.5% or +/-0.25pF	Within +/-10.0%	Set	for 24+/-2h	nours at room temperatur	e, then measure.	
		Change	(Whichever is larger)			Step	1	2	
			20nE min : 0>1000	D7/1.9 · W/ \/ · 25\/ min · 0.005 mov *	-	Temp.(°C)	Min. Operating Temp.+0/-3	Max. Operating Temp.+3/-0	
		Q or D.F.	30pF min. : Q≧1000 30pF max.: Q ≧400+20C	R7/L8 : W.V.: 25V min.: 0.025 max.* *GCG21BL81H104K: 0.03 max.		Time	15+/-3	15+/-3	
			SUPF max.: $Q \leq 400+20C$ C: Nominal Capacitance(pF)	W.V.: 16V : 0.035 max.		(min)	107/-0	67/70	
				R9 : 0.075 max.	1				
					• h	nitial meas	urement for high dielectri	c constant type	
		I.R.	More than $10000M\Omega$ or $500\Omega \cdot F$		Per	form a hea	t treatment at 150+0/-10	°C for 1hour and then sit	
		25°C	(Whichever is smaller)		for 2	24+/-2hour	s at room temperature. P	erform the initial measurement.	

AEC-Q200 Murata Standard Specification and Test Methods

	1		Specif	ication.			
No	AEC-Q2	200 Test Item	Temperature Compensating Type	High Dielectric Type	AEC-Q200 Test Method		
14	ESD	Appearance	No marking defects		Per AEC-Q200-002		
		Capacitance	Within the specified initial value.				
		Q or D.F.	Within the specified initial value.				
		I.R. More than 10000MΩ or 500Ω • F 25°C (Whichever is smaller)					
15	Electrical	25°C Appearance	(Whichever is smaller) No defects or abnormalities		Visual inspection.		
15	Chatacteri-						
	zation	Capacitance	Shown in Rated value.		The capacitance/Q/D.F. should be measured at 25°C at the frequency and voltage shown in the table.		
		Q or D.F.	30pF min. : Q≧1000 30pF max.: Q≧400+20C C: Nominal Capacitance(pF)	R7/L8 : W.V.: 25Vmin.: 0.025 max. W.V.: 16V : 0.035 max. R9 : 0.075 max.	$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$		
		I.R. 25°C	More than 100000MΩ or 1000Ω • F	More than 10000MΩ or 500Ω · F	The insulation resistance should be measured with a DC voltage not		
			(Whichever is smaller)	(Whichever is smaller)	exceeding the rated voltage at 25°C and 125°C(for Δ C/7U/R7)/ 150°C (for 5G/L8/R9) within 2 minutes of charging.		
		I.R. 125°C	More than 10000MΩ or 50Ω • F (Whichever is smaller)	More than 1000MΩ or 10Ω • F (Whichever is smaller)	The charge/discharge current is less than 50mA.		
		I.R. 150°C	More than 10000MΩ or 100Ω · F (Whichever is smaller)	More than 1000MΩ or 1Ω+F (Whichever is smaller)			
		Dielectric Strength	No failure	•	No failure should be observed when 250% of the rated voltage is applied between the terminations for 1 second to 5 seconds. The charge/discharge current is less than 50mA.		
16	Terminal Strength	Appearance	No marking defects		Mount the capacitor on the test substrate in Fig.1 using a conductive glue (HEREAUS"PC3000").		
	Chongin	Capacitance	Within the specified initial value.		The conductive glue is hardened at 140°C for 30 minites. Then apply *shear tension in parallel with the test substrate for 60 seconds.		
		Q or D.F.	Within the specified initial value.		*Show in the table 1		
		I.R. 25°C	More than 10000MΩ or 500Ω ∙F (Whichever is smaller)		Series Share Tension GCG15 2.0N GCG18 2.7N GCG21 4.9N GCG31 6.9N GCG32 12.6N Table.1		
					Ag Pd electrode C Alumina		
					Series a b c GCG15 0.4 1.5 0.5 GCG18 1.0 3.0 1.2 GCG21 1.2 4.0 1.65 GCG31 2.2 5.0 2.0 GCG32 2.2 5.0 2.9 Fig. 1		

■AEC-Q200 Murata Standard Specification and Test Methods

		Spec	ification.			
No AEC-Q	200 Test Item	Temperature Compensating Type	High Dielectric Type	AEC-Q200 Test Method		
17 Beam Load Te	est	Destruction value should be exceed following one. < Chip L dimension : 2.5mm max. > Chip thickness > 0.5mm rank : 20N Chip thickness = 0.5mm rank : 8N < Chip L dimension : 3.2mm mim. > Chip thickness < 1.25mm rank : 15N Chip thickness ≧ 1.25mm rank : 54.5N		Place the capacitor in the beam load fixture as Fig 2. Apply a force. < Chip Length : 2.5mm max. > Iron Board < Chip Length : 3.2mm min. > Iron Board Fig.2 Speed supplied the Stress Load : 0.5mm/s.		
18 Capacitance T Characteristics		Nominal values of the temperature coefficient is shown in Rated value. But, the Capacitance Change under Reference Temp. is shown in Table A. Capacitance Drift Within +/-0.2% or +/-0.05pF (Whichever is larger.)	R7 : Within +/-15% (-55°C to +125°C) L8 : Within +/-15% (-55°C to +125°C) Within +15/-40% (+125°C to +150°C) R9 : Within +/-15% (-55°C to +150°C)	The capacitance change should be measured after 5 minutes at each specified temp. stage. Capacitance value as a reference is the value in step 3. (1)Temperature Compensating Type The capacitance drift is calculated by dividing the differences between the maximum and minimum measured values in the step 1,3 and 5 by the cap. value in step 3. <u>Step Temperature(°C)</u> <u>1 Reference Temp.+/-2</u> <u>2 Min. Operating Temp.+/-3</u> <u>3 Reference Temp.+/-2</u> <u>4 Max. Operating Temp.+/-3</u> <u>5 Reference Temp.+/-2</u> <u>2 Min. Operating Temp.+/-3</u> <u>3 Reference Temp.+/-2</u> <u>4 Max. Operating Temp.+/-3</u> <u>3 Reference Temp.+/-2</u> <u>4 Max. Operating Temp.+/-3</u> <u>3 Reference Temp.+/-2</u> <u>4 Max. Operating Temp.+/-3</u> <u>5 Reference Temp.+/-2</u> <u>4 Hax. Operating Temp.+/-3</u> <u>5 Reference Temp.+/-2</u> <u>4 Hax. Operating Temp.+/-3</u> <u>5 Reference Temp.+/-2</u> <u>4 Hax. Operating Temp.+/-3</u> <u>5 Reference Temp.+/-2</u> <u>5 Reference Temp.+/-2</u> <u>5 Reference Temp.+/-2</u> <u>7 Hax Notice Temp.+/-3</u> <u>7 Reference Temp.+/-2</u> <u>7 Hax Notice Temp.+/-3</u> <u>7 Reference Temp.+/-3</u> <u>7 Reference Temp.+/-2</u> <u>7 Hit Reference Temp.+/-3</u> <u>7 Reference Temp.</u>		

Table A	Capacitance Change be	ween at Reference Temp. a	and at each Temp. (%)

Table A Capacitance Change between at Reference Temp. and at each Temp. (%)										
Char.	-5	55	-3	30	-10					
Char.	Max.	Min.	Max.	Min.	Max.	Min.				
5C/5G	0.58	-0.24	0.40	-0.17	0.25	-0.11				
7U	8.78	5.04	6.04	3.47	3.84	2.21				

1.Tape Carrier Packaging(Packaging Code:D/E/W/F/L/J/K)

1.1 Minimum Quantity(pcs./reel)

			φ180mm reel	φ330mm reel		
	Туре	Pape	r Tape	Plastic Tape	Paper Tape	Plastic Tape
		Code:D/E	Code:W	Code:L	Code:J/F	Code:K
GCH15	5 (Dimensions Tolerance:±0.05)	10000(W8P2)	20000(W8P1)		50000(W8P2)	
GCITIS	5 (Dimensions Tolerance:±0.2)	10000(W8P2)			40000(W8P2)	
GCH18		4000			10000	
	6	4000			10000	
GCH21	9	4000			10000	
	В			3000		10000
	9	4000			10000	
GCH31	Μ			3000		10000
	С			2000		6000
GCH32	D/E			1000		4000

4.0±0.1

0.05 max.

Т

0.5±0.05

0.5±0.2

*2

ſ-ŀ

1.2 Dimensions of Tape

Туре

5

GCH15

(1)GCH15 <Paper Tape W8P2 CODE:D/E/J/F>

*1, 2 : 2.0±0.05

 ϕ 1. 5 $^{+0.1}_{-0}$

1.0±0.05

 \leftrightarrow 1.0 ± 0.05

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-

Dimensions(Chip)

W

0.5±0.05

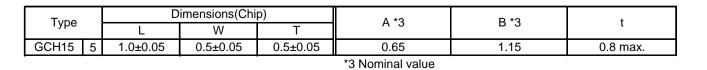
0.5±0.2

(2)GCH15 <Paper Tape W8P1 CODE:W>

L

1.0±0.05

1.0±0.2



*3 Nominal value

A *3

0.65

0.75

1.75±0.1

3.5±0.05

8.0±0.3

(in mm)

t

0.8 max.

(in mm)

Package GCH Tv

muRata

4.0±0.1 1.75±0.1 ϕ 1.5 $^{+0.1}_{-0}$ 02 -3.5±0.0 8.0±0.3 - +- -

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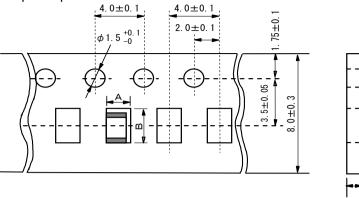
B *3

1.15

1.35

Package GCH<u>Type</u>

(3)GCH18/21/31 <Paper Tape>

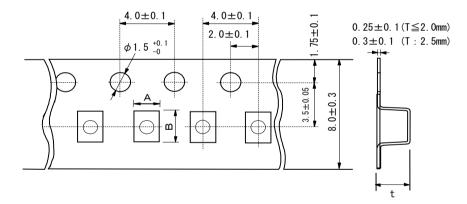


(in mm)

						5	
Туре		Γ	Dimensions(Chip)	٨	р	+
туре		L	W	Т	A	D	ι
GCH18	8	1.6±0.1	0.8±0.1	0.8±0.1	1.05±0.10	1.85±0.10	
GCH21	6	2.0±0.15	1.25±0.15	0.6±0.1	1.55±0.15	2.30±0.15	1.1 max.
GCH2T	9	2.0±0.15	1.25±0.15	0.85±0.1	1.55±0.15	2.30±0.15	1.1 max.
GCH31	9	3.2±0.15	1.6±0.15	0.85±0.1	2.00±0.20	3.60±0.20	

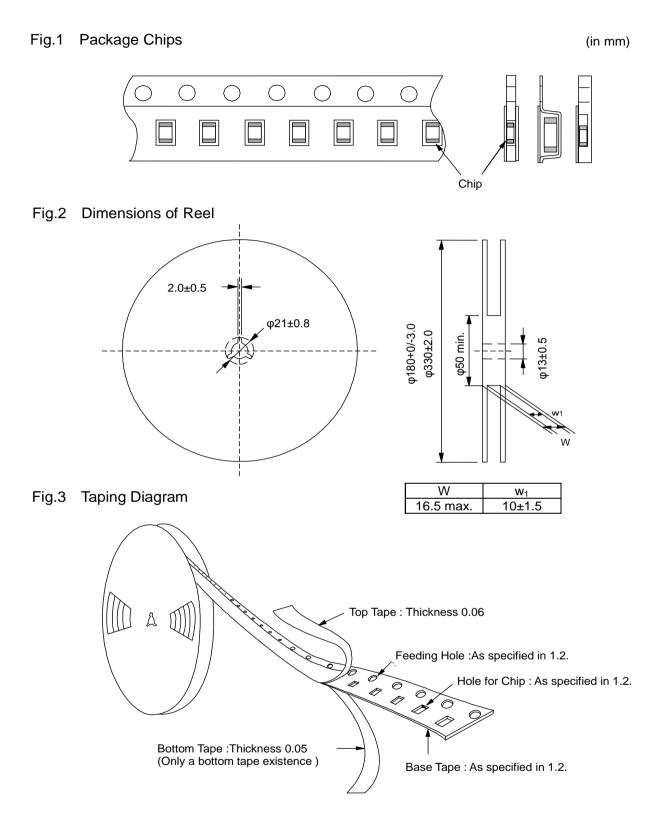
(4)GCH21/31/32 <Plastic Tape>

(in mm)



Туре		C	Dimensions(Chip	o)	А	В	t		
туре		L	W	Т	~	В	L		
GCH21	в	2.0±0.15	1.25±0.15	1.25±0.15	1.45±0.20	2.25±0.20	2.0 max.		
GCH2T	Б	2.0±0.2	1.25±0.2	1.25±0.2	1.50±0.20	2.30±0.20	2.0 max.		
	М	м	м	3.2±0.15	1.6±0.15	1.15±0.1			1.7 max.
GCH31		3.2±0.2	1.6±0.2	1.15±0.15	1.90±0.20	3.50±0.20	1.7 max.		
	С	3.2±0.2	1.6±0.2	1.6±0.2			2.5 max.		
GCH32	D	3.2±0.3	2.5±0.2	2.0±0.2	2.80±0.20	3.50±0.20	3.0 max.		
601132	Е	5.2±0.5	2.0±0.2	2.5±0.2	2.00±0.20	5.50±0.20	3.7 max.		

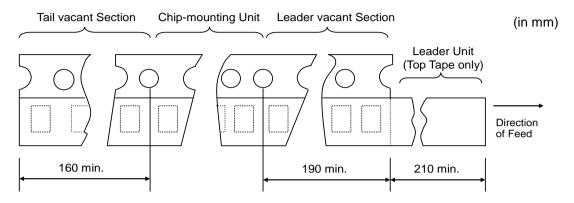
Package GCH Type



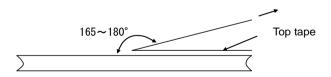
1.3 Tapes for capacitors are wound clockwise shown in Fig.3.

(The sprocket holes are to the right as the tape is pulled toward the user.)

1.4 Part of the leader and part of the vacant section are attached as follows.



- 1.5 Accumulate pitch : 10 of sprocket holes pitch = 40 ± 0.3 mm
- 1.6 Chip in the tape is enclosed by top tape and bottom tape as shown in Fig.1.
- 1.7 The top tape and base tape are not attached at the end of the tape for a minimum of 5 pitches.
- 1.8 There are no jointing for top tape and bottom tape.
- 1.9 There are no fuzz in the cavity.
- 1.10 Break down force of top tape : 5N min. Break down force of bottom tape : 5N min. (Only a bottom tape existence)
- 1.11 Reel is made by resin and appearance and dimension is shown in Fig 2. There are possibly to change the material and dimension due to some impairment.
- 1.12 Peeling off force : 0.1N to 0.6N in the direction as shown below.



1.13 Label that show the customer parts number, our parts number, our company name, inspection number and quantity, will be put in outside of reel.

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects which might directly cause damage to the third party's life, body or property.

①Aircraft equipment
 ②Aerospace equipment
 ③Undersea equipment
 ④Power plant control equipment
 ⑤Medical equipment
 ⑥Transportation equipment(vehicles,trains,ships,etc.)
 ⑦Traffic signal equipment
 ⑧Data-processing equipment
 ⑩Application of similar complexity and/or reliability requirements to the applications listed in the above.

Storage and Operation condition

 If store the chip multilayer ceramic capacitors in an atmosphere consisting of high temperature or humidity, sulfur or chlorine gases, contaminants attach to the surface of external electrode, and bondability with conductive glue may deteriorate. Do not store the capacitors in an atmosphere consisting of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammoria gas, etc.). Storage environment must be at room temperature of +5°C to +40°C and a relative humidity of 20% to 70%, and use the product within six months after receipt.

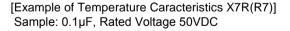
In case of packaging, do not open the last wrappend, polyethylene bag, till just before using. After unpacking, immediately reseal, or store in a desiccator containing a desiccant.

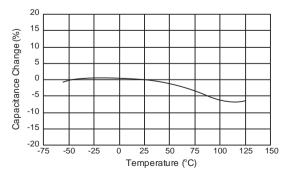
- 2. Due to moisture condensation caused by rapid humidity changes, or the photochemical change caused by direct sunlight on the terminal electrodes and/or the resin/epoxy coatings, the bondability with conductive glue and electrical performance may deteriorate. Do not store capacitors under direct sunlight or in high humidity conditions.
- 3. This product is chip monolithic ceramic capacitor limited to conductive glue mounting. Do not apply mounting method other than conductive glue. Flow or reflow soldering can result in a lack of adhesive strength on the outer electrode by poor wettability, which may result in chips breaking loose from the PCB.

Rating

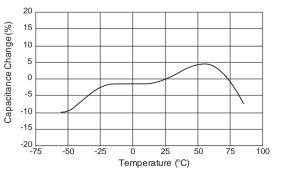
1.Temperature Dependent Characteristics

- 1. The electrical characteristics of the capacitor can change with temperature.
- 1-1. For capacitors having larger temperature dependency, the capacitance may change with temperature changes. The following actions are recommended in order to ensure suitable capacitance values.
 - (1) Select a suitable capacitance for the operating temperature range.
 - (2) The capacitance may change within the rated temperature. When you use a high dielectric constant type capacitor in a circuit that needs a tight (narrow) capacitance tolerance (e.g., a time-constant circuit), please carefully consider the temperature characteristics, and carefully confirm the various characteristics in actual use conditions and the actual system.





[Example of Temperature Characteristics X5R(R6)] Sample: 22µF, Rated Voltage 4VDC



2.Measurement of Capacitance

- 1. Measure capacitance with the voltage and frequency specified in the product specifications.
- 1-1. The output voltage of the measuring equipment may decrease occasionally when capacitance is high. Please confirm whether a prescribed measured voltage is impressed to the capacitor.
- 1-2. The capacitance values of high dielectric constant type capacitors change depending on the AC voltage applied. Please consider the AC voltage characteristics when selecting a capacitor to be used in a AC circuit.

3.Applied Voltage

- 1. Do not apply a voltage to the capacitor that exceeds the rated voltage as called out in the specifications.
- 1-1. Applied voltage between the terminals of a capacitor shall be less than or equal to the rated voltage.
- (1) When AC voltage is superimposed on DC voltage, the zero-to-peak voltage shall not exceed the rated DC voltage. When AC voltage or pulse voltage is applied, the peak-to-peak voltage shall not exceed the rated DC voltage.
- (2) Abnormal voltages (surge voltage, static electricity, pulse voltage, etc.) shall not exceed the rated DC voltage.
- (2) Abhornal voltages (surge voltage, static electricity, puise voltage, etc.) shall not exceed the fated DC voltage



(E : Maximum possible applied voltage.)

1-2. Influence of over voltage

Over voltage that is applied to the capacitor may result in an electrical short circuit caused by the breakdown of the internal dielectric layers .

The time duration until breakdown depends on the applied voltage and the ambient temperature.

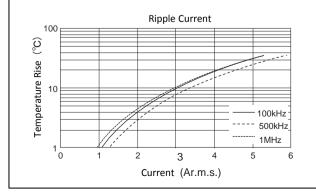
4.Type of Applied Voltage and Self-heating Temperature

1.Confirm the operating conditions to make sure that no large current is flowing into the capacitor due to the continuous application of an AC voltage or pulse voltage.

When a DC rated voltage product is used in an AC voltage circuit or a pulse voltage circuit, the AC current or pulse current will flow into the capacitor; therefore check the self-heating condition.

Please confirm the surface temperature of the capacitor so that the temperature remains within the upper limits of the operating temperature, including the rise in temperature due to self-heating. When the capacitor is used with a high-frequency voltage or pulse voltage, heat may be generated by dielectric loss.

<Applicable to Rated Voltage of less than 100VDC> The load should be contained so that the self-heating of the capacitor body remains below 20°C, when measuring at an ambient temperature of 25°C. [Example of Temperature Rise (Heat Generation) in Chip Multilayer Ceramic Capacitors in Contrast to Ripple Current] Sample: R(R1) characteristics 10μ F, Rated voltage: DC10V



muRata ∆Caution

5. DC Voltage and AC Voltage Characteristic

- The capacitance value of a high dielectric constant type capacitor changes depending on the DC voltage applied. Please consider the DC voltage characteristics when a capacitor is selected for use in a DC circuit.
- 1-1. The capacitance of ceramic capacitors may change sharply depending on the applied voltage. (See figure) Please confirm the following in order to secure the capacitance.
- (1) Determine whether the capacitance change caused by the applied voltage is within the allowed range .
- (2) In the DC voltage characteristics, the rate of capacitance change becomes larger as voltage increases, even if the applied voltage is below the rated voltage. When a high dielectric constant type capacitor is used in a circuit that requires a tight (narrow) capacitance tolerance (e.g., a time constant circuit), please carefully consider the voltage characteristics, and confirm the various characteristics in the actual operating conditions of the system.
- The capacitance values of high dielectric constant type capacitors changes depending on the AC voltage applied.
 Please consider the AC voltage characteristics when selecting a capacitor to be used in a AC circuit.

6. Capacitance Aging

 The high dielectric constant type capacitors have an Aging characteristic in which the capacitance value decreases with the passage of time. When you use a high dielectric constant type capacitors in a circuit that needs a tight (narrow) capacitance tolerance (e.g., a time-constant circuit), please carefully consider the characteristics of these capacitors, such as their aging, voltage, and temperature characteristics. In addition, check capacitors using your actual appliances at the intended environment and operating conditions.

7.Vibration and Shock

- 1. Please confirm the kind of vibration and/or shock, its condition, and any generation of resonance. Please mount the capacitor so as not to generate resonance, and do not allow any impact on the terminals.
- Mechanical shock due to being dropped may cause damage or a crack in the dielectric material of the capacitor. Do not use a dropped capacitor because the quality and reliability may be deteriorated.
- 3. When printed circuit boards are piled up or handled, the corner of another printed circuit board should not be allowed to hit the capacitor in order to avoid a crack or other damage to the capacitor.







[Example of Change Over Time (Aging characteristics)]





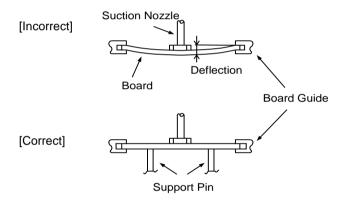
Mounting

1. Selection of Conductive Adhesive, Mounting Process, and Bonding Strength

1. The acuired bonding strength may change greatly depending on the conductive adhesive to be used. Be sure to confirming the desired performance can be acquired in the assumed monting process with the conductive adhesive to be used.

2.Maintenance of the Mounting (pick and place) Machine

- 1. Make sure that the following excessive forces are not applied to the capacitors. Check the mounting in the actual device under actual use conditions ahead of time.
- 1-1. In mounting the capacitors on the printed circuit board, any bending force against them shall be kept to a minimum to prevent them from any damage or cracking. Please take into account the following precautions and recommendations for use in your process.
 - (1) Adjust the lowest position of the pickup nozzle so as not to bend the printed circuit board.



2.Dirt particles and dust accumulated in the suction nozzle and suction mechanism prevent the nozzle from moving smoothly. This creates excessive force on the capacitor during mounting, causing cracked chips. Also, the locating claw, when worn out, imposes uneven forces on the chip when positioning, causing cracked chips. The suction nozzle and the locating claw must be maintained, checked and replaced periodically.

3.Moisture proof

1.To prevent the silver electrode migration, keep parts under low moisture condition with resin coating and the equivalent.

4.Coating

 A crack may be caused in the capacitor due to the stress of the thermal contraction of the resin during curing process. The stress is affected by the amount of resin and curing contraction. Select a resin with low curing contraction. The difference in the thermal expansion coefficient between a coating resin or a molding resin and the capacitor may cause the destruction and deterioration of the capacitor such as a crack or peeling, and lead to the deterioration of insulation resistance or dielectric breakdown.

Select a resin for which the thermal expansion coefficient is as close to that of the capacitor as possible. A silicone resin can be used as an under-coating to buffer against the stress.

- Select a resin that is less hygroscopic. Using hygroscopic resins under high humidity conditions may cause the deterioration of the insulation resistance of a capacitor. An epoxy resin can be used as a less hygroscopic resin.
- 3. The halogen system substance and organic acid are included in coating material, and a chip corrodes by the kind of Coating material. Do not use strong acid type.

Others

1. Under Operation of Equipment

- 1-1. Do not touch a capacitor directly with bare hands during operation in order to avoid the danger of an electric shock.
- 1-2. Do not allow the terminals of a capacitor to come in contact with any conductive objects (short-circuit). Do not expose a capacitor to a conductive liquid, inducing any acid or alkali solutions.
- 1-3. Confirm the environment in which the equipment will operate is under the specified conditions.
 - Do not use the equipment under the following environments.
 - (1) Being spattered with water or oil.
 - (2) Being exposed to direct sunlight.
 - (3) Being exposed to ozone, ultraviolet rays, or radiation.
 - (4) Being exposed to toxic gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
 - (5) Any vibrations or mechanical shocks exceeding the specified limits.
 - (6) Moisture condensing environments.
- 1-4. Use damp proof countermeasures if using under any conditions that can cause condensation.

2. Others

- 2-1. In an Emergency
- (1) If the equipment should generate smoke, fire, or smell, immediately turn off or unplug the equipment. If the equipment is not turned off or unplugged, the hazards may be worsened by supplying continuous power.
- (2) In this type of situation, do not allow face and hands to come in contact with the capacitor or burns may be caused by the capacitor's high temperature.
- 2-2. Disposal of waste

When capacitors are disposed of, they must be burned or buried by an industrial waste vendor with the appropriate licenses.

- 2-3. Circuit Design
- (1) Addition of Fail Safe Function

Capacitors that are cracked by dropping or bending of the board may cause deterioration of the insulation resistance, and result in a short. If the circuit being used may cause an electrical shock, smoke or fire when a capacitor is shorted, be sure to install fail-safe functions, such as a fuse, to prevent secondary accidents.

(2) This series are not safety standard certified products.

2-4. Remarks

Failure to follow the cautions may result, worst case, in a short circuit and smoking when the product is used. The above notices are for standard applications and conditions. Contact us when the products are used in special mounting conditions.

Select optimum conditions for operation as they determine the reliability of the product after assembly. The data herein are given in typical values, not guaranteed ratings.

muRata Notice

Rating

1.Operating Temperature

- 1. The operating temperature limit depends on the capacitor.
- 1-1. Do not apply temperatures exceeding the maximum operating temperature.
 It is necessary to select a capacitor with a suitable rated temperature that will cover the operating temperature range.
 It is also necessary to consider the temperature distribution in equipment and the seasonal temperature variable factor.
- 1-2. Consider the self-heating factor of the capacitor The surface temperature of the capacitor shall not exceed the maximum operating temperature including self-heating.

2.Atmosphere Surroundings (gaseous and liquid)

- 1. Restriction on the operating environment of capacitors.
- 1-1. Capacitors, when used in the above, unsuitable, operating environments may deteriorate due to the corrosion of the terminations and the penetration of moisture into the capacitor.
- 1-2. The same phenomenon as the above may occur when the electrodes or terminals of the capacitor are subject to moisture condensation.
- 1-3. The deterioration of characteristics and insulation resistance due to the oxidization or corrosion of terminal electrodes may result in breakdown when the capacitor is exposed to corrosive or volatile gases or solvents for long periods of time.

3.Piezo-electric Phenomenon

1. When using high dielectric constant type capacitors in AC or pulse circuits, the capacitor itself vibrates at specific frequencies and noise may be generated. Moreover, when the mechanical vibration or shock is added to capacitor, noise may occur.

Others

1.Transportation

- 1. The performance of a capacitor may be affected by the conditions during transportation.
- 1-1. The capacitors shall be protected against excessive temperature, humidity and mechanical force during transportation.
 - (1) Climatic condition
 - low air temperature : -40°C
 - change of temperature air/air : -25°C/+25°C
 - · low air pressure : 30 kPa
 - · change of air pressure : 6 kPa/min.

(2) Mechanical condition

Transportation shall be done in such a way that the boxes are not deformed and forces are not directly passed on to the inner packaging.

- 1-2. Do not apply excessive vibration, shock, or pressure to the capacitor.
 - (1) When excessive mechanical shock or pressure is applied to a capacitor, chipping or cracking may occur in the ceramic body of the capacitor.
 - (2) When the sharp edge of an air driver, tweezers, a chassis, etc. impacts strongly on the surface of the capacitor, the capacitor may crack and short-circuit.
- 1-3. Do not use a capacitor to which excessive shock was applied by dropping etc. A capacitor dropped accidentally during processing may be damaged.

2.Characteristics Evaluation in the Actual System

- 1. Evaluate the capacitor in the actual system, to confirm that there is no problem with the performance and specification values in a finished product before using.
- 2. Since a voltage dependency and temperature dependency exists in the capacitance of high dielectric type ceramic capacitors, the capacitance may change depending on the operating conditions in the actual system. Therefore, be sure to evaluate the various characteristics, such as the leakage current and noise absorptivity, which will affect the capacitance value of the capacitor.
- 3. In addition, voltages exceeding the predetermined surge may be applied to the capacitor by the inductance in the actual system. Evaluate the surge resistance in the actual system as required.

- 1.Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
- 2. Your are requested not to use our product deviating from this product specification.
- 3.We consider it not appropriate to include any terms and conditions with regard to the business transaction in the product specifications, drawings or other technical documents. Therefore, if your technical documents as above include such terms and conditions such as warranty clause, product liability clause, or intellectual property infringement liability clause, they will be deemed to be invalid.